
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wang et al.

Attorney Docket No.: ALTRP100/A1198

Application No.: 10/719,218

Examiner: RAO, Shrinivas H.

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL AND DESIGN Confirmation No.: 3208
FOR ASSEMBLING A LOW-K Si DIE TO
ACHIEVE AN INDUSTRIAL GRADE
RELIABILITY WIRE BONDING PACKAGE

CERTIFICATE OF EFS-WEB TRANSMISSION

I hereby certify that this correspondence is being transmitted electronically through EFS-WEB to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450 on March 9, 2007.

Signed: /Linda L. Quintana/
Linda L. Quintana

AMENDMENT C

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Office Action mailed December 13, 2006, please consider the following remarks and amend the above-identified Application as follows.

Amendments to the Claims are reflected in the listing of claims, which begin on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.